

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	9	"5696389".pn. "6468824".pn. "20030155579" "5869849".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/23 16:43
S2	176	(led or light near emitting near diode) and (al near ga near in near p or ga near al near in near n or in near ga near as or zna near se or algaip or gaalip or gaalinn or algaip or ingaas or ingaip or ingaap or inalga or znsse) and (copper or cu) near10 (plated or plating or electroplat \$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/23 16:51
S3	0	(led or light near emitting near diode) and (active or quantum near well or qw or mqw) and (selectiv\$4) near6 (plated or plating or electroplat\$4) near8 (scribe or scribing or cleav\$4 or dicing or singulation or street or diced)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 09:03
S4	5	(led or light near emitting near diode) and (active or quantum near well or qw or mqw) and (copper or cu) near6 (plated or plating or electroplat\$4) near8 (scribe or scribing or cleav\$4 or dicing or singulation or street or diced)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 09:04

S5	66	(copper or cu) near6 (plated or plating or electroplat\$4) near8 (scribe or scribing or cleav\$4 or dicing or singulation or street or diced)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 09:05
S6	430	257/94.ccls. and (conductive or metal or metallic or copper or cu or plated or plating or electroplated or electroplating) near3 (substrate or submount or carrier)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 09:19
S7	218	257/94.ccls. and (mirror or reflector or reflection) and (algainp or gaalinp or inalgap or gaalinn or inalgan or ingaas or znsse or al near2 ga near2 in near2 p or al near2 ga near2 in near2 n or in near2 ga near2 as or zn near2 se)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 09:38
S8	230	257/96.ccls. and (conductive or metal or metallic or copper or cu or plated or plating or electroplated or electroplating) near3 (substrate or submount or carrier)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 09:54
S9	145	257/96.ccls. and (mirror or reflector or reflection) and (algainp or gaalinp or inalgap or gaalinn or inalgan or ingaas or znsse or al near2 ga near2 in near2 p or al near2 ga near2 in near2 n or in near2 ga near2 as or zn near2 se)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 10:04

S10	510	257/98.ccls. and (conductive or metal or metallic or copper or cu or plated or plating or electroplated or electroplating) near3 (substrate or submount or carrier) and (mirror or reflecting or reflector)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 10:28
S11	390	257/98.ccls. and (mirror or reflector or reflection) and (algaipn or gaalinp or inalgap or gaalinn or inalgan or ingaas or znsse or al near2 ga near2 in near2 p or al near2 ga near2 in near2 n or in near2 ga near2 as or zn near2 se)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 10:38
S12	411	257/99.ccls. and (conductive or metal or metallic or copper or cu or plated or plating or electroplated or electroplating) near3 (substrate or submount or carrier) and (mirror or reflecting or reflector)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 10:48
S13	218	257/99.ccls. and (mirror or reflector or reflection) and (algaipn or gaalinp or inalgap or gaalinn or inalgan or ingaas or znsse or al near2 ga near2 in near2 p or al near2 ga near2 in near2 n or in near2 ga near2 as or zn near2 se)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 11:11

S15	335	257/103.ccls. and (conductive or metal or metallic or copper or cu or plated or plating or electroplated or electroplating) near3 (substrate or submount or carrier) and (mirror or reflecting or reflector)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 17:57
S16	290	257/103.ccls. and (mirror or reflector or reflection) and (algaip or gaalip or inalgap or gaalinn or inalgan or ingaas or znse or al near2 ga near2 in near2 p or al near2 ga near2 in near2 n or in near2 ga near2 as or zn near2 se)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 18:13
S17	6	(copper or metal or metallic or cu) near5 (substrate or submount or base or carrier or holder or heatsink or mount) and (copper or metal or metallic or cu) near4 (selectiv\$4 near4 (deposit\$4 or plating or plated or electroplat\$4) near20 (scribe or scribing or cleav\$4 or dicing or diced or singulation or singulating or singulated or street or lane)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/30 08:24

S18	243	(copper or metal or metallic or cu) near5 (substrate or submount or base or carrier or holder or heatsink or mount) and (led or light near emitting near diode) and (active or qw or mqw or quantum adj well) near10 (algainp or inalgap or ingaalp or gaalinn or ingaaln or inalgan or ingaas or znsse or al near2 ga near2 in near2 (p or n) or in near2 ga near2 as or zn near2 se near2 sl) and (mirror or reflect\$4) near6 (cladding or under or beneath or lower or below or underlying)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/30 08:28
S19	11	(copper or metal or metallic or cu) near4 (selectiv\$4) near4 (deposit\$4 or plating or plated or electroplat \$4) near20 (scribe or scribing or cleav\$4 or dicing or diced or singulation or singulating or singulated or street or lane)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/30 09:01
S20	78	257/e33.026.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/30 09:02
S21	150	257/e33.056.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/30 09:07

S22	373	257/e33.068.ccls. and (conductive or metal or metallic or copper or cu or plated or plating or electroplated or electroplating) near3 (substrate or submount or carrier)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/30 09:24
S23	241	257/e33.068.ccls. and (mirror or reflector or reflection) and (algaipn or gaalipn or inalgap or gaalinn or inalgan or ingaas or znsse or al near2 ga near2 in near2 p or al near2 ga near2 in near2 n or in near2 ga near2 as or zn near2 se)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/30 09:30
S24	318	257/e33.075.ccls. and (conductive or metal or metallic or copper or cu or plated or plating or electroplated or electroplating) near3 (substrate or submount or carrier)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/30 10:31
S25	48	257/e33.075.ccls. and (mirror or reflector or reflection) and (algaipn or gaalipn or inalgap or gaalinn or inalgan or ingaas or znsse or al near2 ga near2 in near2 p or al near2 ga near2 in near2 n or in near2 ga near2 as or zn near2 se)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/30 10:32
S26	17	(selectiv\$4) near3 (plating or plated or electroplat\$4) near10 (dicing or scribe or scribing or cleave or cleaving or cleavage or singulat\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/06 20:06
S27	2	(US-20030231683-\$). did. or (JP-08250804-\$).did.	US-PGPUB; JPO	OR	ON	2008/02/09 09:53

S28	1108	(led or light near emitting near diode) and (mirror or reflect\$4) and (plated or plating or electroplat\$4) near4 (carrier or substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/09 10:37
S29	55	(led or light near emitting near diode) and (active or qw or mqw or quantum near well) and (cladding) and (mirror or reflect\$4) and (plated or plating or electroplat\$4) near4 (carrier or substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/09 10:38
S30	77	(active or qw or mqw or quantum near well) near10 (cladding) and (mirror or reflect\$4) and (plated or plating or electroplat\$4) near6 (carrier or substrate or submount or heatsink or heat near sink\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/09 10:39
S31	110	(led or light near emitting near diode) and (active or qw or mqw or quantum near well) and (cladding) and (plated or plating or electroplat\$4) near8 (carrier or substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/09 17:55
S32	3	(US-20030231683-\$). did. or (US-6649437-\$).did. or (JP-08250804-\$).did.	US-PGPUB; USPAT; JPO	OR	ON	2008/02/09 18:40

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